

DZ2J150

Silicon epitaxial planar type

For constant voltage / waveform clipper and surge absorption circuit

Low noise type

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
SMini2-F5-B
- Pin Name
1. Cathode
2. Anode

■ Marking Symbol: UJ, UU

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *	P_T	200	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $P_T = 200$ mW achieved with a printed circuit board.

■ Common Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA			1.0	V
Zener voltage *1,2,4	V_Z	$I_Z = 5$ mA	14.25		15.60	V
Zener operating resistance	R_Z	$I_Z = 5$ mA			40	Ω
Zener rise operating resistance	R_{ZK}	$I_Z = 0.5$ mA			80	Ω
Reverse current	I_R	$V_R = 11$ V			0.05	μA
Temperature coefficient of zener voltage *3	S_Z	$I_Z = 5$ mA		13.4		mV/ $^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

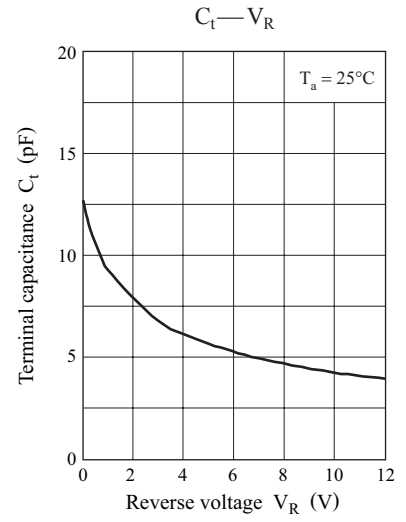
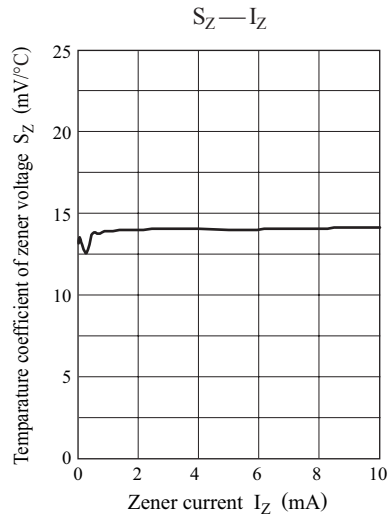
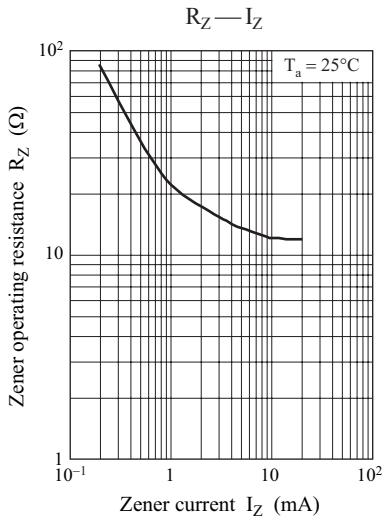
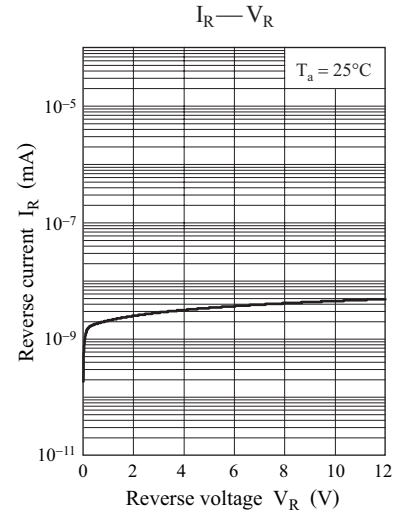
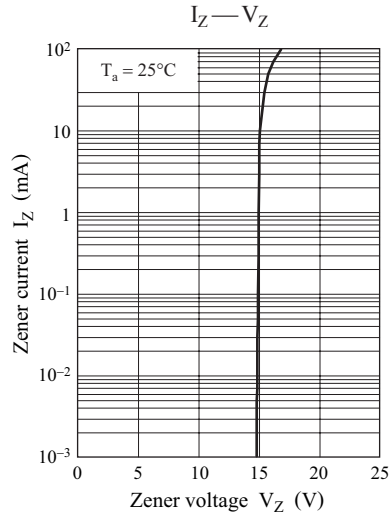
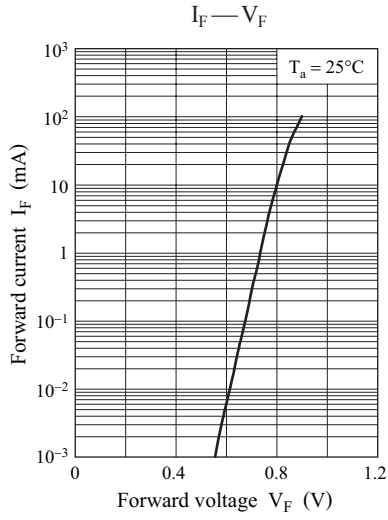
3. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to $V_Z(25^\circ\text{C})$

*2: V_Z guaranteed 20 ms after current flow.

*3: $T_j = 25^\circ\text{C}$ to 150°C

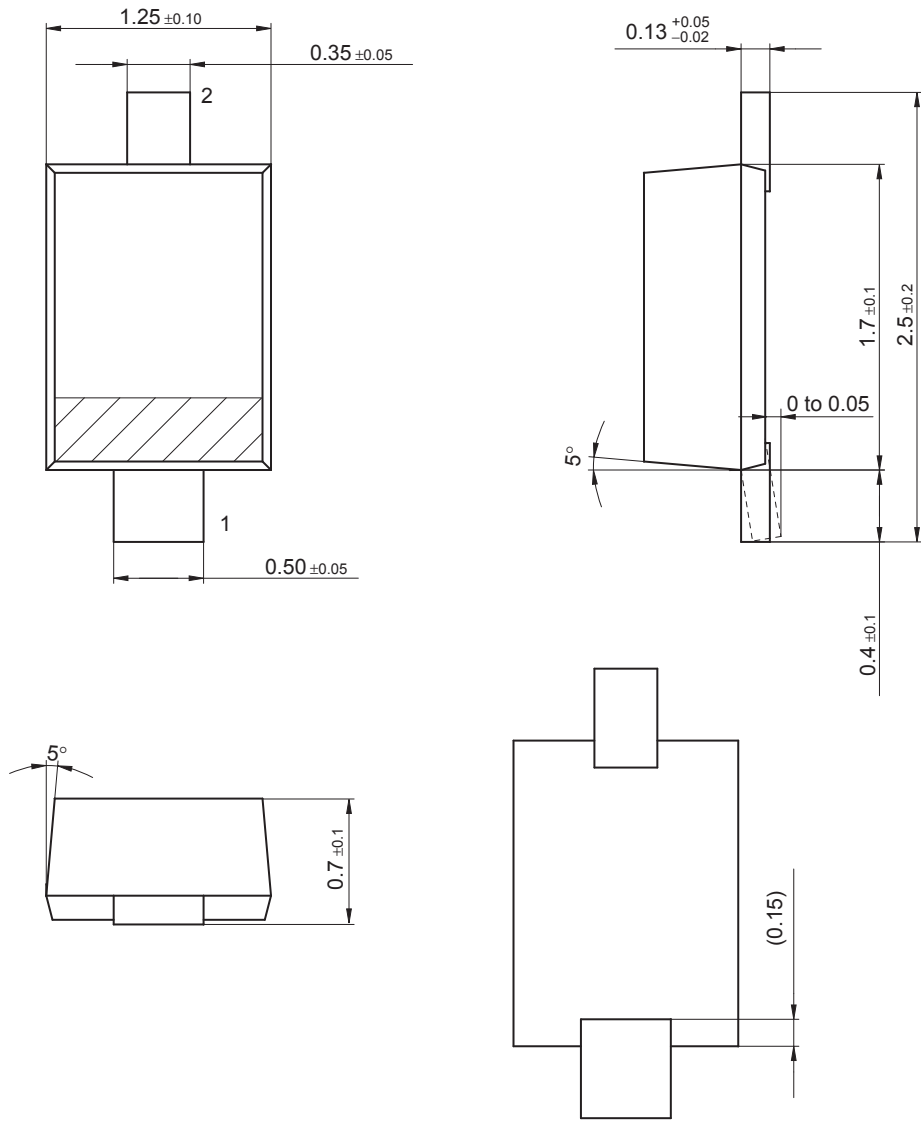
*4: Rank classification

Code	M	0
Rank	M	No-rank
V_Z	14.61 to 15.35	14.25 to 15.60
Marking Symbol	UU	UJ



SMini2-F5-B

Unit: mm



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